

RECEIVED  
CENTRAL FAX CENTER

APR 21 2008

**AMENDMENTS TO THE SPECIFICATION****Please amend the paragraph beginning on page 1, line 21 as follows:**

[0003] Because of the need for the surface mounting of components, these piezoelectric resonator devices are increasingly being housed hermetically inside a package composed of a ceramic material. For instance, Patent Document 1 discloses a package comprising a base (substrate) with a concave cross section having four electrode pads (connecting electrodes) for the mounting of a crystal plate on the front and back faces ~~of~~ on which are formed drive electrodes, and a cap (lid) with an inverted concave cross section, wherein this package is composed of a ceramic material and these components are hermetically sealed. Here, of the four electrode pads, two electrode pads that are opposite to each other in the long-side direction are connected to each other and given the same potential by connecting electrodes (metal wiring), so that two pairs of electrode pads are disposed in linear symmetry around the base center, so when a crystal plate is electromechanically joined to the pairs of electrode pads by a conductive joining material, the assembly can be carried out without worrying about directionality in mounting, and this makes the work easier. Also, with the package configuration disclosed in Patent Document 1, it is possible either for the crystal plate to be supported at just one end in the long-side direction, or for it to be supported at both ends in the long-side direction, which gives this configuration wider applicability.

**Please amend the paragraph beginning on page 2, line 13 as follows:**

**DISCLOSURE SUMMARY OF THE INVENTION PROBLEM TO BE SOLVED BY THE INVENTION**

**Please amend the paragraph beginning on page 2, line 15 as follows:**

[0004] The above-mentioned packages used with piezoelectric resonator devices have been steadily decreasing in weight, thickness, and size in recent years, and a configuration in which the drive electrodes are moved closer to the ends of the piezoelectric resonator element and formed as large as possible, so as to ensure a good effective area, has come to be employed so as not to diminish the electrical characteristics of a piezoelectric resonator element, such as its CI value or frequency sensitivity, when it is made smaller in size. However, when a piezoelectric resonator element with a configuration such as this is used for the package of the above-mentioned Patent Document 1, since there are electrode pads of the different potential in the long-side direction or the short-side direction, a problem is that the drive electrodes of the piezoelectric resonator element may short out by coming into contact with any of the electrode pads of the package. Forming the drive electrodes of the piezoelectric resonator element such that they will not short out with the electrode pads of the package not only imposes design limitations on the dimensions, but also leads to diminished electrical characteristics of the piezoelectric resonator element, and since misalignment and other such ~~error~~has errors have to be factored in when mounting the piezoelectric resonator element in the package, such a package is very much at odds with the goal of reducing the size of the package.

**Please amend the paragraph beginning on page 3, line 13 as follows:**

[0006] To achieve the stated object, the piezoelectric resonator element package according to the present invention is a piezoelectric resonator element package having a base that holds a piezoelectric resonator element on the front and back sides ~~of~~on which are formed drive electrodes, and a cap for hermetically sealing the piezoelectric resonator element, with the piezoelectric resonator element being held on an internal bottom surface of the base, four electrode pads that electrically connect to the drive electrodes of the piezoelectric resonator element being formed on the internal bottom surface of the base, at least one of these electrode pads having the different potential, and avoidance means being provided for avoiding electrical connection between the electrode pad/pads with the different potential and the other electrode pad/pads with the same potential.

**Please amend the paragraph beginning on page 9, line 4 as follows:**

[0024] Also, to achieve the stated object, the piezoelectric resonator according to the present invention is provided with the above-mentioned piezoelectric resonator element package and a piezoelectric resonator element on the front and back sides of ~~on~~ which are formed drive electrodes, the piezoelectric resonator element is held on the internal bottom surface of the base, and the electrode pads of the base and the drive electrodes of the piezoelectric resonator element are electrically connected.

**Please amend the paragraph beginning on page 12, line 12 as follows:**

~~BEST MODE FOR CARRYING OUT THE INVENTION~~ DETAILED DESCRIPTION OF  
PREFERRED EMBODIMENTS

**Please amend the paragraph beginning on page 13, line 10 as follows:**

[0034] The base 1 is, for example, ~~consist~~ consisted of an alumina ceramic material, and comprises a base bottom that is rectangular in plan view, and a frame whose external size is substantially the same as that of the base bottom, but which has a large hole made in its center portion. These layers are laminated and integrally fired. After the firing for molding, a glass layer 11a is formed on the upper surface of the frame by baking or another such method. That is, the base 1 is configured such that it has a receptacle 10 that is concave in cross section and holds the crystal plate 3. The glass layer 11a is formed all the way around and over a bank 11 encircling the recess. The base 1 and the cap 2 can be hermetically sealed even without forming the glass layer 11a, but forming the glass layer 11a increases the joining strength. Castellations C1 and C2 are formed in the center portion of both ends in the long-side direction at the top and bottom of the outer periphery of the base 1, and castellations C3, C4, C5, and C6 are formed in the four corners. Linking electrodes 121 and 131 are formed beneath the castellations C1 and C2, and are electrically connected to terminal electrodes 12 and 13 that are connected to the outside (see FIG. 3).

**Please amend the paragraph beginning on page 20, line 16 as follows:**

[0056] Also, a surface mount device of a crystal resonator was used as an example in the first embodiment above, but the present invention can also be applied to other surface mount piezoelectric resonator devices used in electronic devices such as crystal filters and crystal oscillators.